



SOT1397-10

WLCSP20, wafer level chip-size package, 20 terminals, 0.4 mm pitch, 2.1 mm x 1.7 mm x 0.49 mm body (backside coating included)

25 October 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP20
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	S (silicon)
Mounting method type	S (surface mount)
Issue date	07-07-2022
Manufacturer package code	98ASA01955D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.07	2.1	2.13	mm
package width	1.67	1.7	1.73	mm
seated height	-	0.49	0.53	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	20	-	



WLCSP20, wafer level chip-size package, 20 terminals, 0.4 mm pitch, 2.1 mm x 1.7 mm x 0.49 mm body
(backside coating included)

2 Package outline

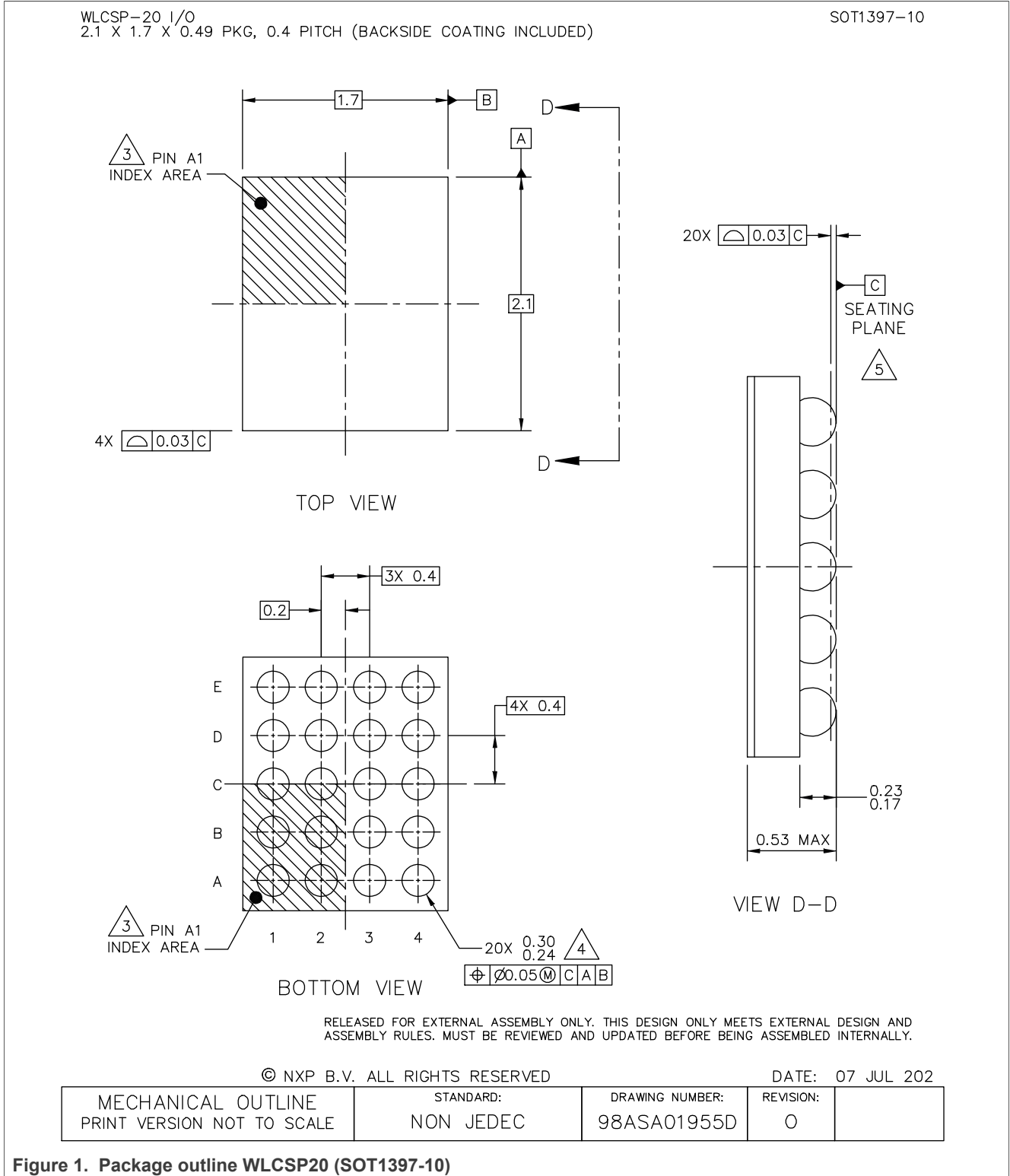
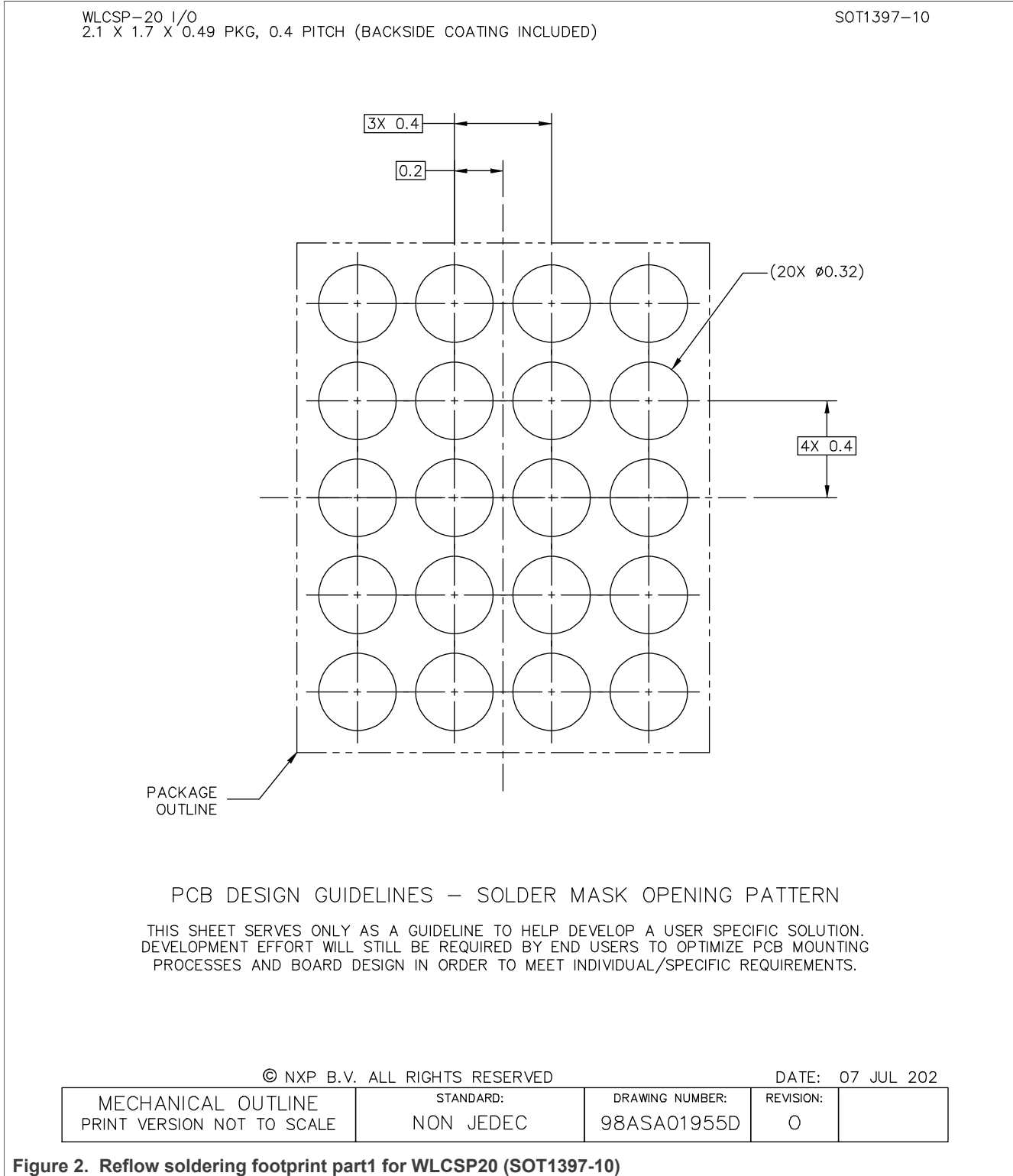


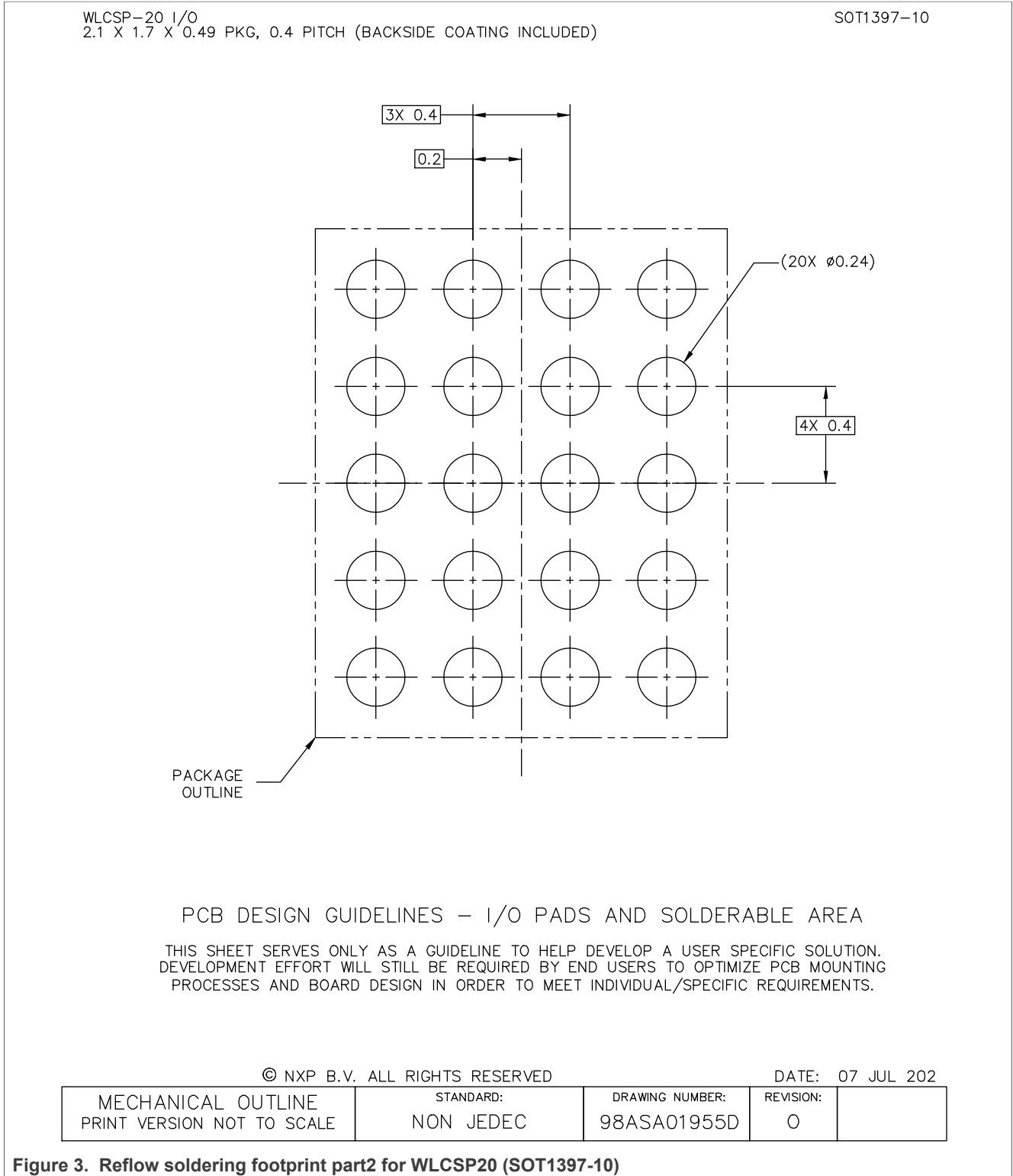
Figure 1. Package outline WLCSP20 (SOT1397-10)

WLCSP20, wafer level chip-size package, 20 terminals, 0.4 mm pitch, 2.1 mm x 1.7 mm x 0.49 mm body (backside coating included)

3 Soldering



WLCSP20, wafer level chip-size package, 20 terminals, 0.4 mm pitch, 2.1 mm x 1.7 mm x 0.49 mm body
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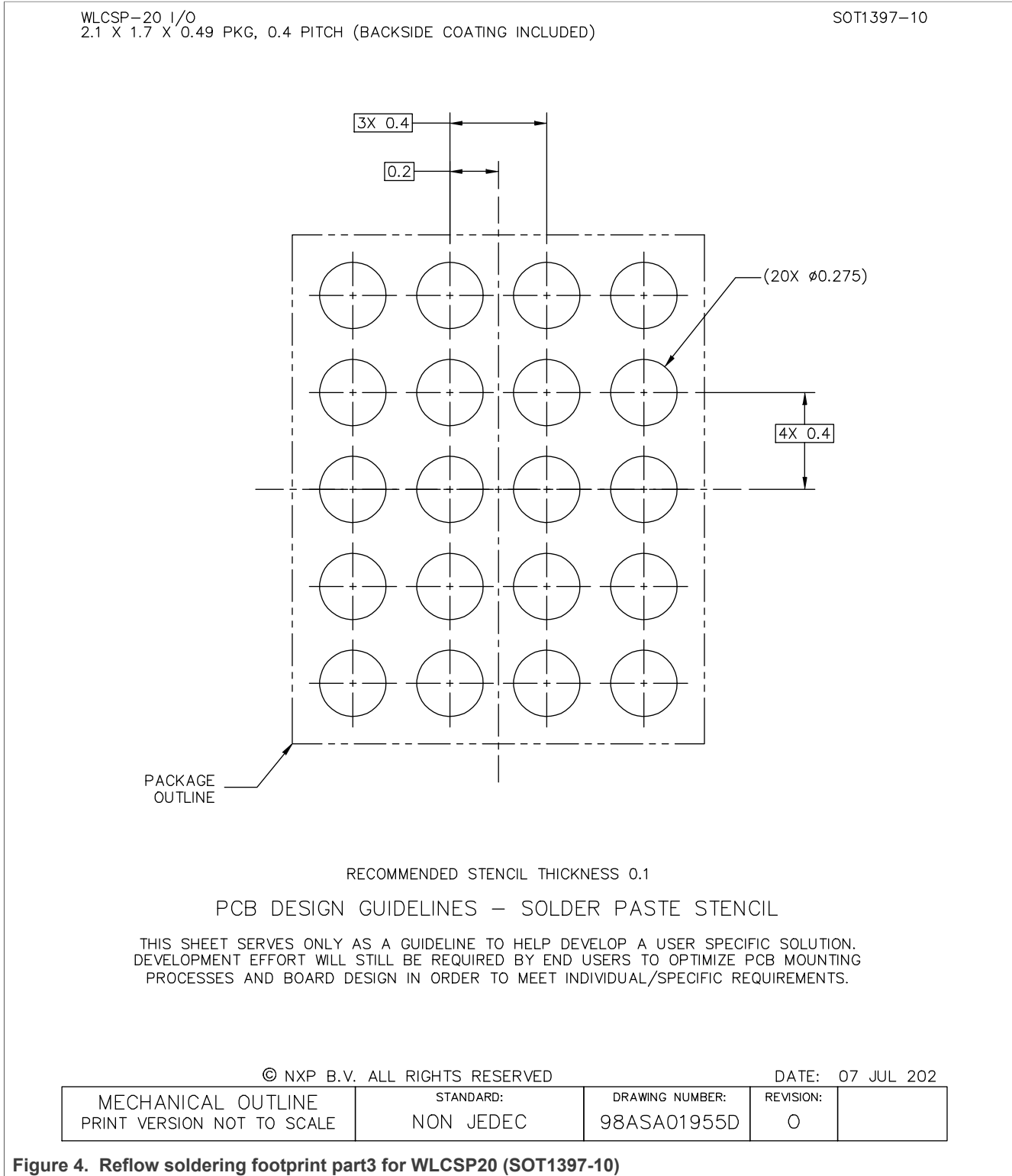


Figure 4. Reflow soldering footprint part3 for WLCSP20 (SOT1397-10)

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WLCSP-20 I/O
2.1 X 1.7 X 0.49 PKG, 0.4 PITCH (BACKSIDE COATING INCLUDED)

SOT1397-10

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.04.

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DATE: 07 JUL 202

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01955D	REVISION: 0	
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Figure 5. Package outline note WLCSP20 (SOT1397-10)

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4 Legal information

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